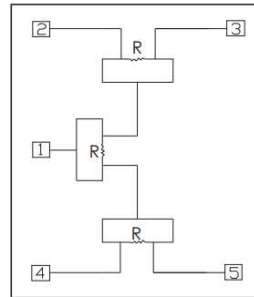


Performance

- Frequency: 2~18GHz
- Insertion loss: 2.0dB
- Chip size: 3.85*4.30*0.1mm

Function Diagram

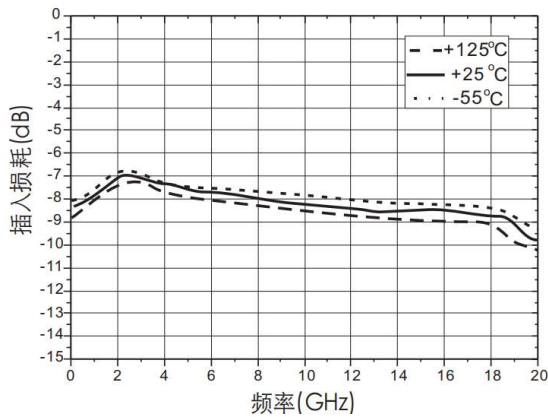


Electrical Specifications (Ta=+25°C, 50Ω system)

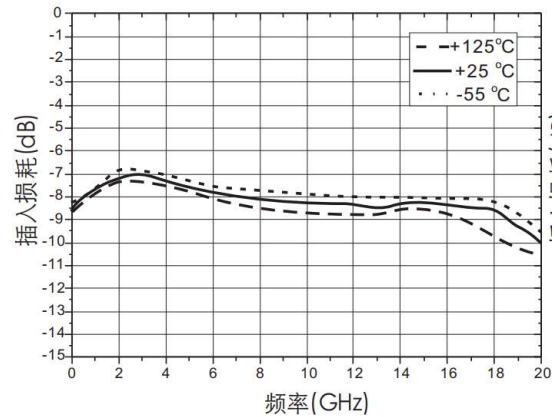
Parameter	Min	Typical	Max	Unit
Frequency Range		2~18		GHz
Insertion Loss	-	2.0	2.8	dB
Insertion Loss Ripple	-	±0.8	-	dB
Isolation	15	20	-	dB
Input Return Loss	10	15	-	dB
Output Return Loss	15	18	-	dB

Test Curves

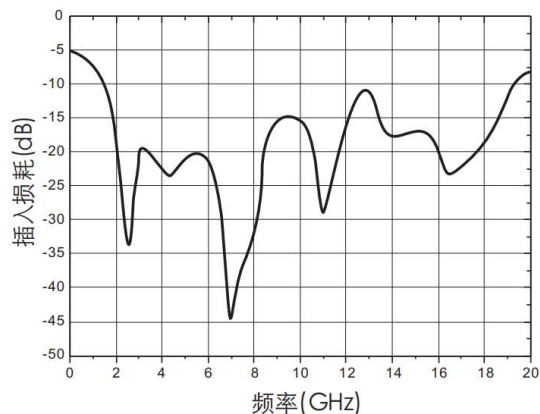
2/4 Port Insertion loss vs. Freq



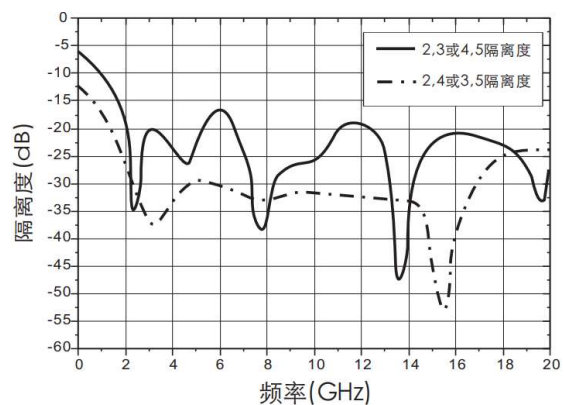
3/5 Port Insertion loss vs. Freq

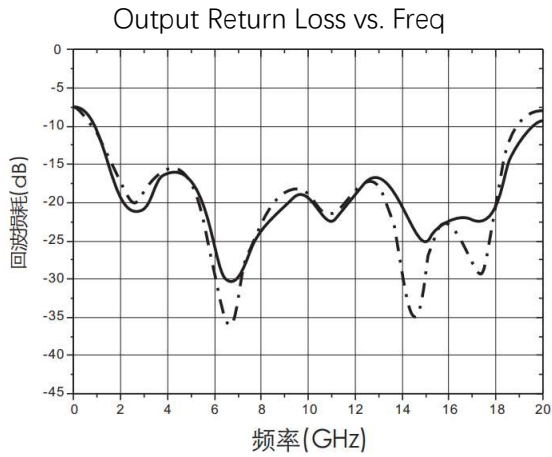


Input Return Loss vs. Freq



Isolation vs. Freq





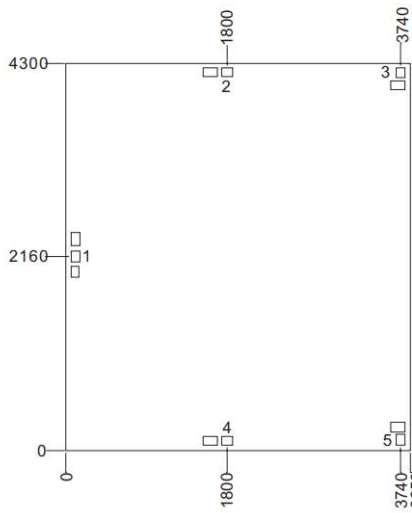
Absolute Max Ratings

Parameter	Value
Input Signal Power	+37dBm
Storage Temperature	-65~150°C
Operating Temperature	-55~125°C
Junction Temperature	175°C
Static protection Grade (HBM)	Class 1C



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

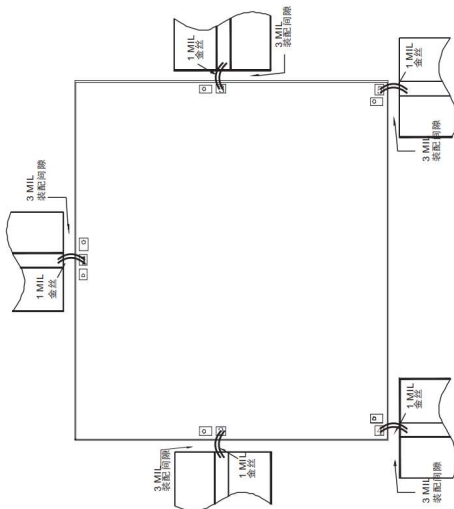
Outline Size



Note:

1. Unit: um
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated
Pads size: 120*100 um
5. Don't bonding on thru holds
6. Tolerance: ±50um

Assembly Diagram



Bonding Definition

No.	Symbol	Description
1	IN	RF input, 50ohm
2,3,4,5	Out1,Out2, Out3,Out4	RF Output, 50ohm
-	GND	Bottom must be grounded